

Mushroom Extrusions



TechSIL Mushroom Extrusions are available in ten different profiles. They can be used in a large groove to control the compression forces or can have either Conductive or non-Conductive Pressure Sensitive Adhesive applied for easy assembly. When using a non-Conductive Adhesive only 50% of the mating surface should have PSA applied. The Mushroom Extrusion can be bonded into O-Rings or Picture Frame gaskets using an RTV cold bond or a Hot Vulcanized bond.

The Mushroom profile offers a much wider operating range and lower compression forces are required than for the Solid versions.

Additional sizes are available upon request.

Features and Benefits

- Superior Reliability
- Cost Effective
- Flexible Design

Typical Applications

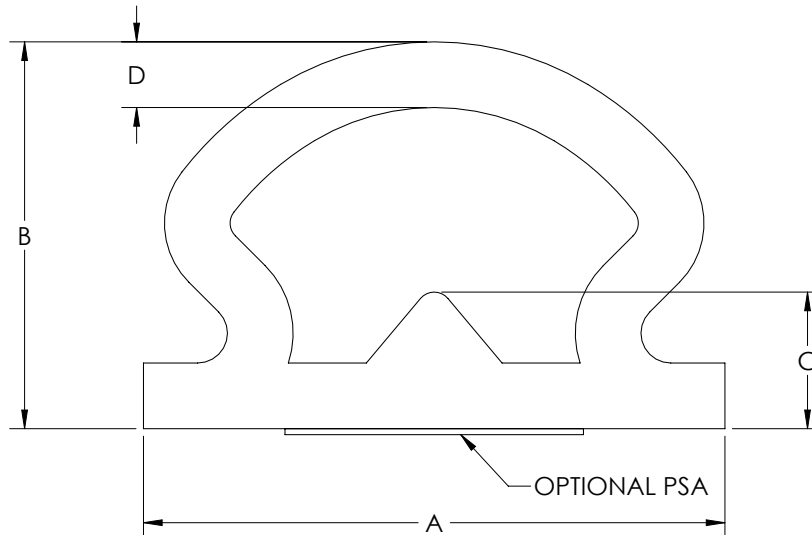
- Defense
- Aerospace
- Consumer electronics
- Telecom
- Industrial
- Automotive
- Life science

MATERIAL CODE	MIL-DTL-83528 MATERIAL TYPE	COLOR	ELASTOMER	FILLER
LTE-10	A	TAN	SIL (Silicone)	Ag/Cu (Silver Plated Copper)
LTE-20	B	TAN	SIL (Silicone)	Ag/Al (Silver Plated Aluminum)
LTE-20B	-	BLUE	SIL (Silicone)	Ag/Al (Silver Plated Aluminum)
LTE-25	H	TAN	SIL (Silicone)	Ag (Silver)
LTE-30	C	TAN	F.SIL (Fluorosilicone)	Ag/Cu (Silver Plated Copper)
LTE-35	F	TAN	F.SIL (Fluorosilicone)	Ag (Silver)
LTE-40	D	TAN	F.SIL (Fluorosilicone)	Ag/Al (Silver Plated Aluminum)
LTE-40B	-	BLUE	F.SIL (Fluorosilicone)	Ag/Al (Silver Plated Aluminum)
LTE-40BLK	-	BLACK	F.SIL (Fluorosilicone)	Ag/Al (Silver Plated Aluminum)
LTE-40-45D	-	TAN	F.SIL (Fluorosilicone)	Ag/Al (Silver Plated Aluminum)
LTE-45	K	TAN	SIL (Silicone)	Ag/Cu (Silver Plated Copper)
LTE-45B	-	BLUE	SIL (Silicone)	Ag/Cu (Silver Plated Copper)
LTE-50	M	TAN	SIL (Silicone)	(Silver Plated Glass)
LTE-55	E	TAN	SIL (Silicone)	Ag (Silver)
LTE-55-50D	-	TAN	SIL (Silicone)	Ag (Silver)
LTE-60	-	BLACK	SIL (Silicone)	Ni/C (Nickel Plated Graphite)
LTE-60-70D	-	BLACK	SIL (Silicone)	Ni/C (Nickel Plated Graphite)
LTE-65	L	TAN	SIL (Silicone)	Ag/Ni (Silver Plated Nickel)
LTE-76	-	TAN	SIL (Silicone)	Ag (Silver)
LTE-80	-	TAN	F.SIL (Fluorosilicone)	Ag/Ni (Silver Plated Nickel)
LTE-90	-	BLACK	F.SIL (Fluorosilicone)	Ni/C (Nickel Plated Graphite)
LTE-90DG	-	DARK GREEN	F.SIL (Fluorosilicone)	Ni/C (Nickel Plated Graphite)



**MUSHROOM
EXTRUSIONS**

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Leader Tech P/N	A (in)	A (mm)	B (in)	B (mm)	C (in)	C (mm)	D (in)	D (mm)
5420-0004-XX	0.265	6.73	0.312	7.92	0.113	2.87	0.040	1.02
5420-0006-XX	0.315	8.00	0.301	7.65	0.109	2.77	0.053	1.35
5420-0002-XX	0.463	11.76	0.428	10.87	0.115	2.92	0.048	1.22
5420-0001-XX	0.472	11.99	0.433	11.00	0.115	2.92	0.040	1.02
5420-0008-XX	0.487	12.37	0.324	8.23	0.115	2.92	0.055	1.40
5420-0010-XX	0.625	15.88	0.375	9.53	0.106	2.69	0.057	1.45
5420-0012-XX	0.625	15.88	0.400	10.16	0.106	2.69	0.057	1.45
5420-0014-XX	0.645	16.38	0.427	10.85	0.065	1.65	0.067	1.70
5420-0016-XX	0.846	21.49	0.472	11.99	0.120	3.05	0.053	1.35
5420-0018-XX	0.890	22.61	0.730	18.54	0.183	4.65	0.065	1.65

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